Preferred Device

# **Surface Mount Schottky Power Rectifier**

... employing the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system.

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guardring for Stress Protection

#### **Mechanical Characteristics**

- Case: Epoxy, Molded, Epoxy Meets UL94, V0
- Weight: 217 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 16 mm Tape and Reel, 2500 units per reel
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- Marking: B54
- ESD Rating: Machine Model, C (> 400 V) Human Body Model, 3B (> 8000 V)
- Device Meets MSL 1 Requirements

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
Average Rectified Forward Current (At Rated V <sub>R</sub> , T <sub>C</sub> = 105°C)	I <sub>F(AV)</sub>	5	Α
Peak Repetitive Forward Current (At Rated V <sub>R</sub> , Square Wave, 20 KHz, T <sub>C</sub> = 80°C)	I <sub>FRM</sub>	10	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	190	A
Storage Temperature Range	Tstg	-65 to +150	°C
Operating Junction Temperature	TJ	-65 to +125	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/μs



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# SCHOTTKY BARRIER RECTIFIER 5.0 AMPERES 40 VOLTS



SMC CASE 403 PLASTIC

### MARKING DIAGRAM



B54 = Specific Device Code

Y = Year W = Work Week

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>	
MBRS540T3	SMC	2500/Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction-to-Case	$R_{\theta JC}$	12	°C/W
Thermal Resistance — Junction-to-Ambient (Note 1)	$R_{\theta JA}$	111	

#### **ELECTRICAL CHARACTERISTICS**

Maximum Instantaneous Forward Voltage (Note 2)	$(i_F = 5.0 \text{ A}, T_C = 25^{\circ}\text{C})$	V <sub>F</sub>	0.50	V
Maximum Instantaneous Reverse Current (Note 2)	(Rated dc Voltage, T <sub>C</sub> = 25°C) (Rated dc Voltage, T <sub>C</sub> = 100°C)	i <sub>R</sub>	0.3 15	mA

- 1. Rating applies when surface mounted on the minimum pad size recommended.
- 2. Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

### **TYPICAL CHARACTERISTICS**

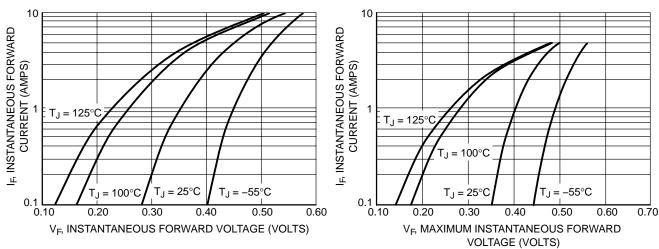
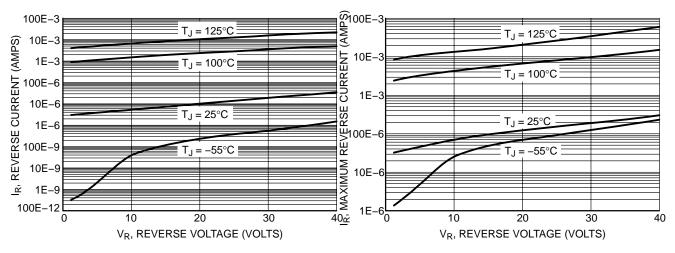


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



**Figure 3. Typical Reverse Current** 

**Figure 4. Maximum Reverse Current** 

### **TYPICAL CHARACTERISTICS**

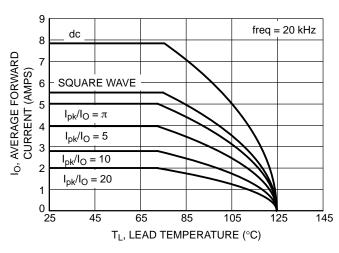
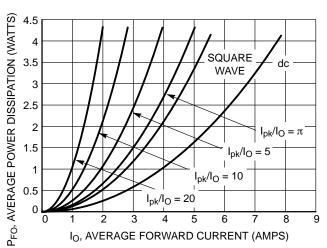


Figure 5. Current Derating



**Figure 6. Forward Power Dissipation** 

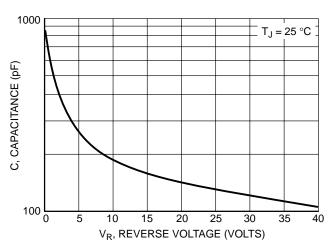


Figure 7. Capacitance

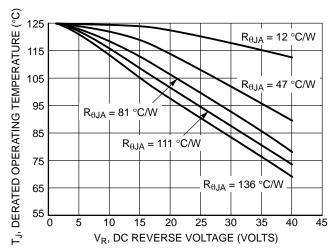


Figure 8. Typical Operating Temperature Derating

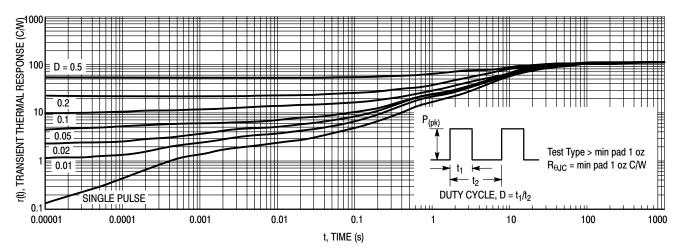


Figure 9. Thermal Response - MBRS540T3 on min pad

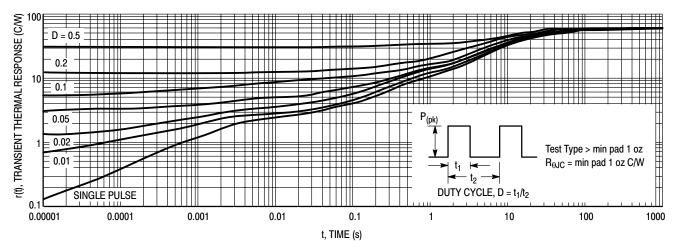
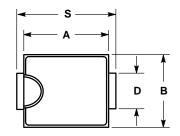
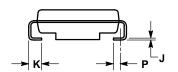


Figure 10. Thermal Response - MBRS540T3 on 1" pad

## **PACKAGE DIMENSIONS**

 ${\bf SMC}$ CASE 403-03 ISSUE D



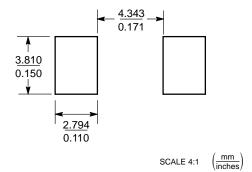




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.
  4. 403-01 THRU -02 OBSOLETE, NEW STANDARD 403-03.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.260	0.280	6.60	7.11	
В	0.220	0.240	5.59	6.10	
С	0.075	0.095	1.90	2.41	
D	0.115	0.121	2.92	3.07	
Н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
Р	0.020 REF		0.51 REF		
S	0.305	0.320	7.75	8.13	

# RECOMMENDED FOOTPRINT FOR SMC



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